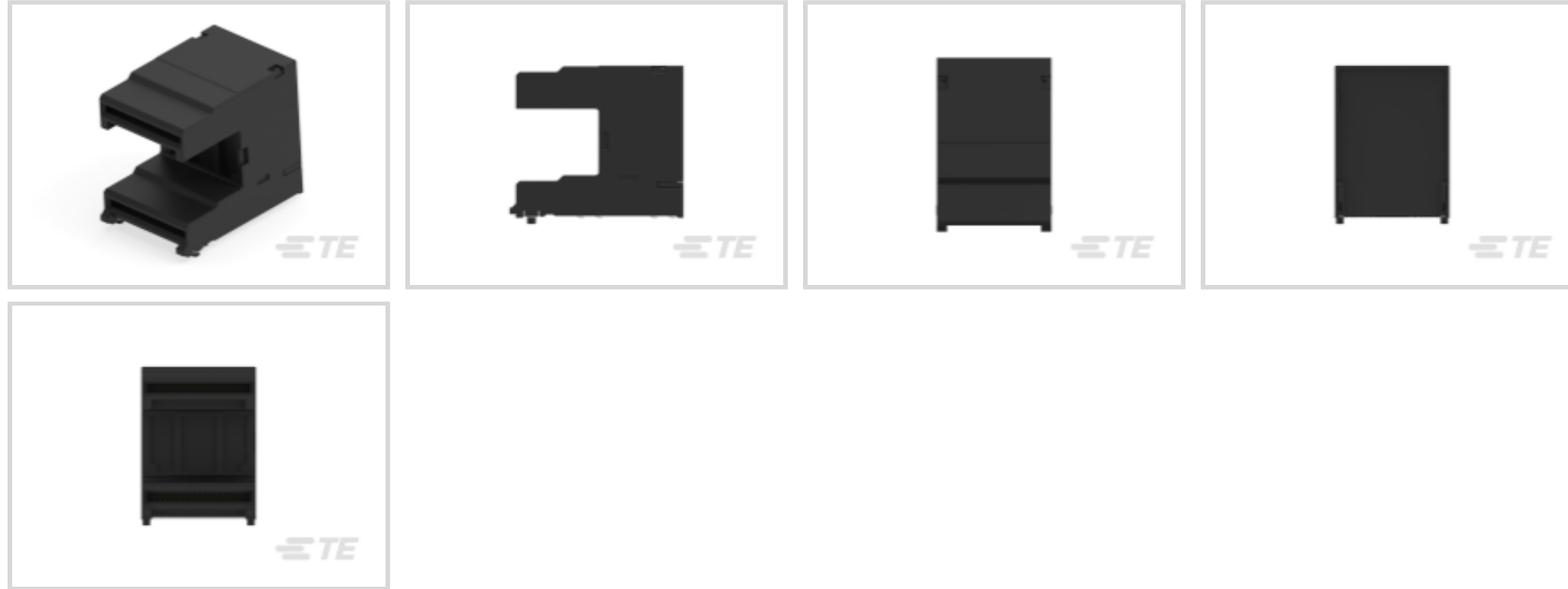




TE Internal #: 2394949-2
 QSFP112, Connector, .031in [.8mm] Centerline, Signal, Operating Temperature Range -55 – 105 °C [-67 – 185 °F], Data Rate (Max) 112 Gb/s, 76 Position

[View on TE.com >](#)

Connectors > Pluggable IO Connectors & Cages



Pluggable I/O Product Type: **Connector**
 Centerline (Pitch): **.8 mm [.031 in]**
 Circuit Application: **Signal**
 Operating Temperature Range: **-55 – 105 °C [-67 – 185 °F]**
 Data Rate (Max): **112 Gb/s**

Features

Product Type Features

Pluggable I/O Product Type	Connector
Form Factor	QSFP112

Configuration Features

Number of Positions	76
Number of Ports	2
Port Matrix Configuration	2 x 1

Electrical Characteristics

Data Rate (Max)	112 Gb/s
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Contact Features

Contact Mating Area Plating Material	Gold
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	.5 A

Termination Features



Termination Method to Printed Circuit Board	Surface Mount
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Housing Features

Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	.8 mm [.031 in]

Usage Conditions

Operating Temperature Range	-55 – 105 °C [-67 – 185 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tray/Box
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

[RCPT CONN QSFP 112 STACKED](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2394949-2_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2394949-2_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2394949-2_1.3d_stp.zip](#)

English

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Product Specifications

[Product Specification](#)

English